



**Synchronous Buck
 Multiphase Optimized BGA Power Block**
 Integrated Power Semiconductors, Drivers & Passives

Features:

- Output current 30A continuous with no derating up to $T_{PCB} = 90^{\circ}\text{C}$ and $T_{CASE} = 90^{\circ}\text{C}$
- Operating frequency up to 1MHz
- Dual sided heatsink capable
- Very small 11mm x 11mm x 2.6mm profile
- iP2001PbF footprint compatible
- Internal features minimize layout sensitivity *
- Optimized for very low power losses



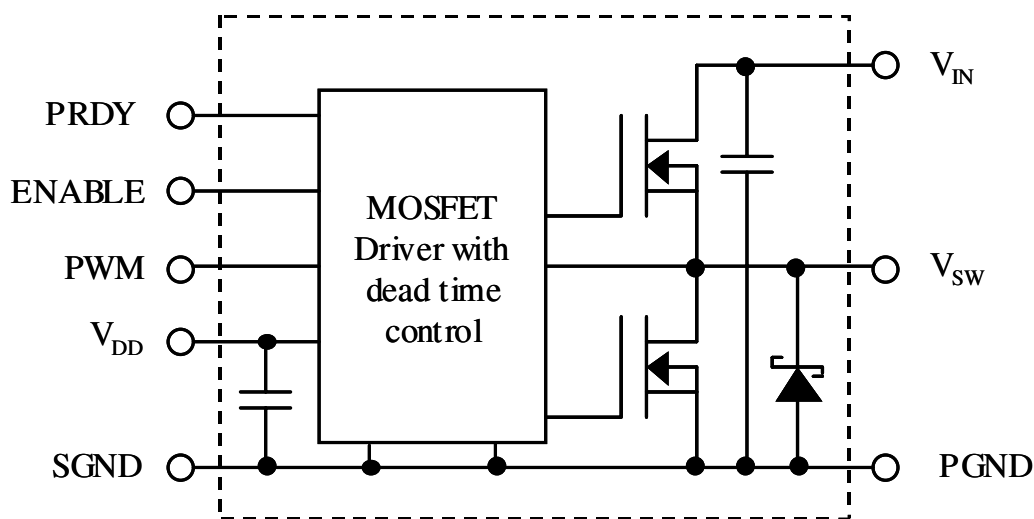
iP2002PbF Power Block

Description

The iP2002PbF is a fully optimized solution for high current synchronous buck multiphase applications. Board space and design time are greatly reduced because most of the components required for each phase of a typical discrete-based multiphase circuit are integrated into a single 11mm x 11mm x 2.6mm BGA power block. The only additional components required for a complete multiphase converter are a PWM IC, the external inductors, and the input and output capacitors.

iPOWIR technology offers designers an innovative board space saving solution for applications requiring high power densities. iPOWIR technology eases design for applications where component integration offers benefits in performance and functionality. iPOWIR technology solutions are also optimized internally for layout, heat transfer and component selection.

iP2002PbF Internal Block Diagram



* All of the difficult PCB layout and bypassing issues have been addressed with the internal design of the iPOWIR Block. There are no concerns about double pulsing, unwanted shutdown, or other malfunctions which often occur in switching power supplies. The iPOWIR Block will function normally without any additional input power supply bypass capacitors. However, for reliable long term operation it is recommended that at least four 10uF ceramic input decoupling capacitors are provided to the V_{IN} pin of each power block. No additional

iP2002PbF

All specifications @ 25°C (unless otherwise specified)

Absolute Maximum Ratings :

| Parameter | Min | Typ | Max | Units | Conditions |
|-------------------------|------|-----|----------------------|-------|--------------------|
| V _{IN} to PGND | - | - | 16 | V | |
| V _{DD} to SGND | - | - | 6.0 | V | |
| PWM to SGND | -0.3 | - | V _{DD} +0.3 | V | not to exceed 6.0V |
| Enable to SGND | -0.3 | - | V _{DD} +0.3 | V | not to exceed 6.0V |
| Output RMS Current | - | - | 30 | A | |
| Block Temperature | -40 | - | 125 | °C | |

Recommended Operating Conditions :

| Parameter | Symbol | Min | Typ | Max | Units | Conditions |
|----------------------|------------------|-----|-----|------|-------|--------------------|
| Supply Voltage | V _{DD} | 4.6 | 5.0 | 5.5 | V | |
| Input Voltage Range | V _{IN} | 3.0 | - | 13.2 | V | see Figs. 2 & 3 |
| Output Voltage Range | V _{OUT} | 0.8 | - | 3.3 | V | see Figs. 2, 4 & 8 |
| Output Current Range | I _{OUT} | - | - | 30 | A | see Fig. 2 |
| Operating Frequency | f _{sw} | 150 | - | 1000 | kHz | see Figs. 2 & 5 |
| Operating Duty Cycle | D | - | - | 85 | % | |

Electrical Specifications @ V_{DD} = 5V (unless otherwise specified) :

| Parameter | Symbol | Min | Typ | Max | Units | Conditions |
|-----------------------------------|-----------------------|-----|-----|-----|-------|---|
| Block Power Loss ① | P _{BLK} | - | 7.2 | 8.9 | W | V _{IN} = 12V, V _{OUT} = 1.3V, I _{OUT} = 30A, f _{sw} = 1MHz |
| Turn On Delay ② | t _{d(on)} | - | 63 | - | ns | |
| Turn Off Delay ② | t _{d(off)} | - | 26 | - | | |
| V _{IN} Quiescent Current | I _{Q-VIN} | - | - | 1.0 | mA | Enable = 0V, V _{IN} = 12V |
| V _{DD} Quiescent Current | I _{Q-VDD} | - | - | 10 | µA | Enable = 0V, V _{DD} = 5V |
| Under-Voltage Lockout | UVLO | | | | | |
| Start Threshold | V _{START} | 4.2 | 4.4 | 4.5 | V | |
| Hysteresis | V _{Hys-UVLO} | - | .05 | - | | |
| Enable | Enable | | | | | |
| Input Voltage High | V _{IH} | 2.0 | - | - | V | |
| Input Voltage Low | V _{IL} | - | - | 0.8 | | |
| Power Ready | PRDY | | | | | |
| Logic Level High | V _{OH} | 4.5 | 4.6 | - | V | V _{DD} = 4.6V, I _{Load} = 10mA |
| Logic Level Low | V _{OL} | - | 0.1 | 0.2 | | V _{DD} < UVLO Threshold, I _{Load} = 1mA |
| PWM Input | PWM | | | | | |
| Logic Level High | V _{OH} | 2.0 | - | - | V | |
| Logic Level Low | V _{OL} | - | - | 0.8 | | |

① Measurement were made using four 10uF (TDK C3225X7R1C106M or equiv.) capacitors across the input (see Fig. 8).

② Not associated with the rise and fall times. Does not affect Power Loss (see Fig. 9).

Pin Description Table

| Pin Name | Ball Designator | Pin Function |
|-----------------|---|--|
| V _{DD} | A1 – A3, B1 – B3 | Supply voltage for the internal circuitry. |
| V _{IN} | A5 – A12, B5 – B12, C5 - C10 | Input voltage for the DC-DC converter. |
| PGND | C11, C12, D11, D12, E11, E12, F6, F7, F12, G6, G7, G12, H6, H7, H12, J6, J7, J12, K5 – K7, K12, L5, L6, L12, M5 – M7, M12 | Power Ground - connection to the ground of bulk and filter capacitors. |
| V _{SW} | D5 – D10, E5 – E10, F8 – F11, G8 – G11, H8 – H11, J8 – J11, K8 – K11, L8 – L11, M8 – M11 | Switching Node - connection to the output inductor. |
| SGND | C1 – C3, D1 –D3, E1 –E3 | Signal Ground. |
| ENABLE | F1 | When set to logic level high, internal circuitry of the device is enabled. When set to logic level low, the PRDY pin is forced low, the Control and Synchronous switches are turned off, and the supply current is less than 10μA. |
| PRDY | K1 | Power Ready - This pin indicates the status of ENABLE or V _{DD} . This output will be driven low when ENABLE is logic low or when V _{DD} is less than 4.4V (typ.). When ENABLE is logic high and V _{DD} is greater than 4.4V (typ.), this output is driven high. This output has a 10mA source and 1mA sink capability. |
| PWM | H1 | TTL-level input signal to MOSFET drivers. |
| NC | B4, C4, D4, E4, F2 – F4, G2 – G4, H2 – H4, J1, J2 – J4, K3, L1, L2, M1 – M4 | This pin is not for electrical connection. It should be attached only to dead copper. |

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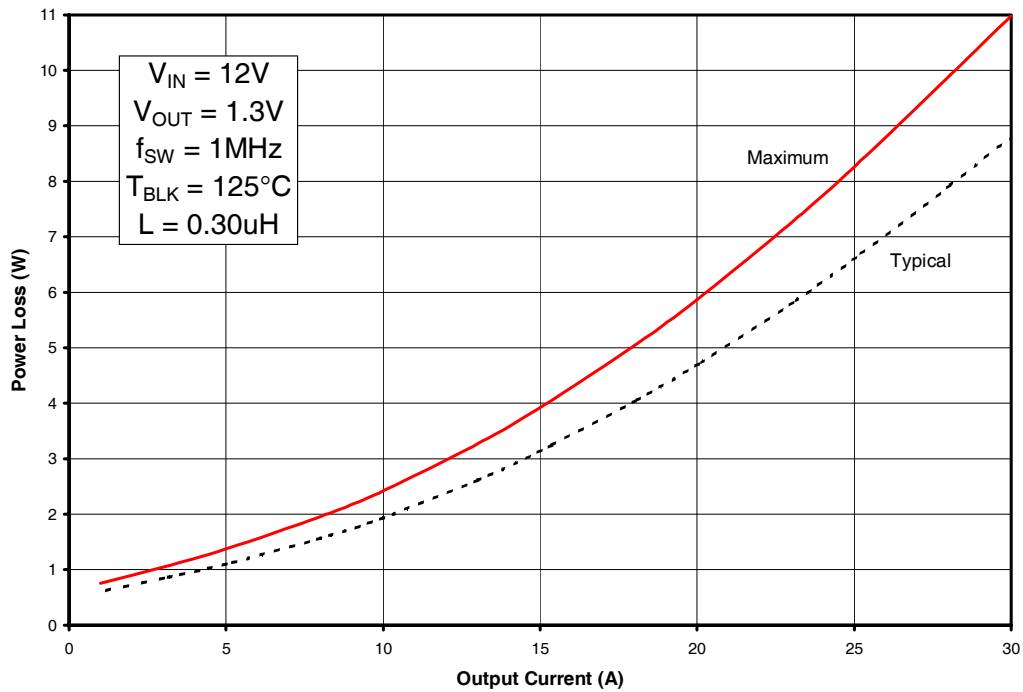


Fig. 1: Power Loss vs. Current

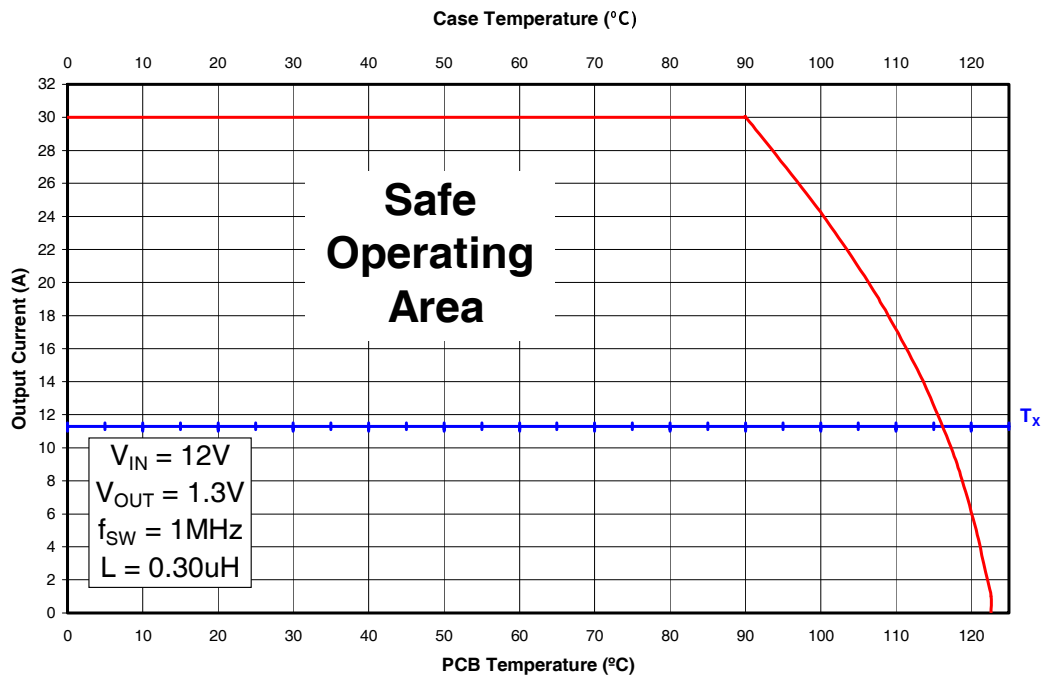


Fig. 2: Safe Operating Area (SOA) vs. T_{PCB} & T_{CASE}

Typical Performance Curves

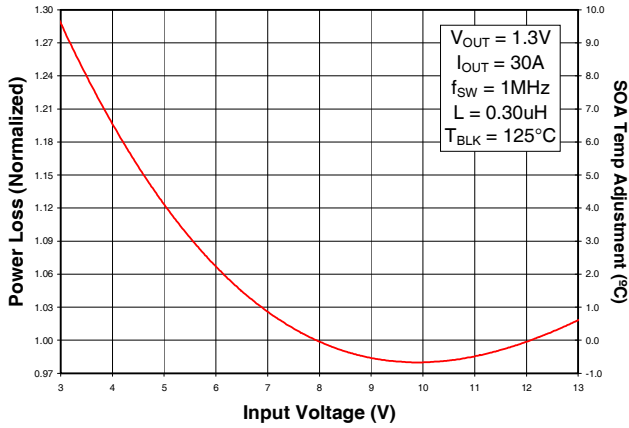


Fig. 3: Normalized Power Loss vs. V_{IN}

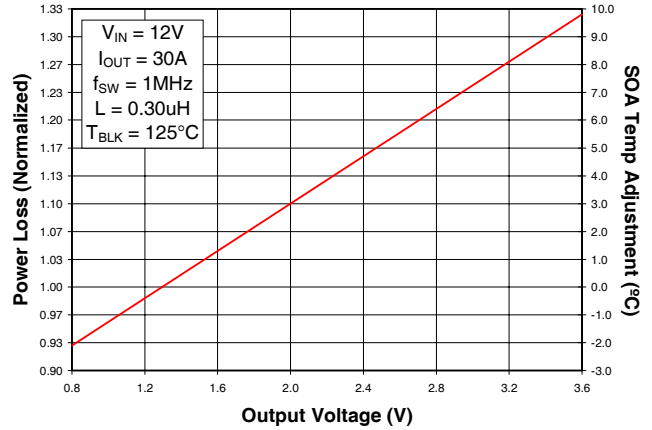


Fig. 4: Normalized Power Loss vs. V_{OUT}

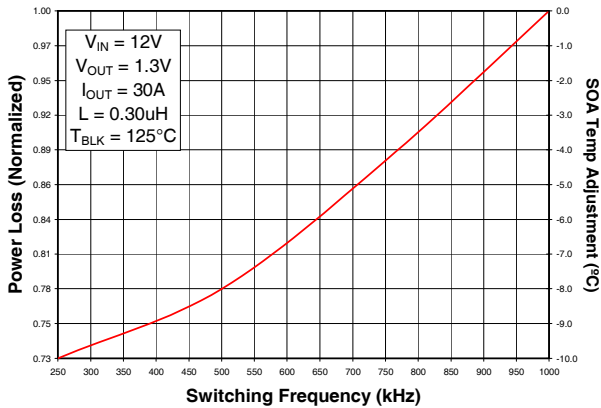


Fig. 5: Normalized Power Loss vs. Frequency

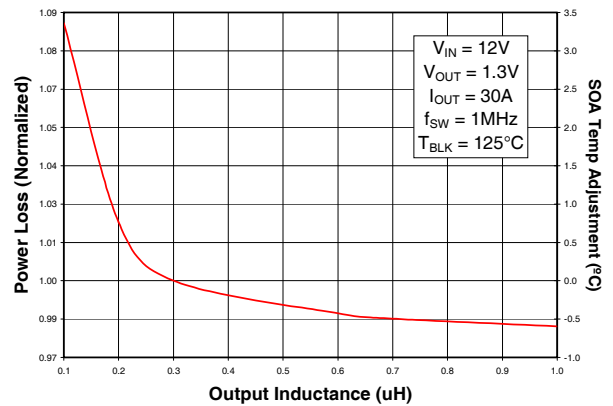


Fig. 6: Normalized Power Loss vs. Inductance

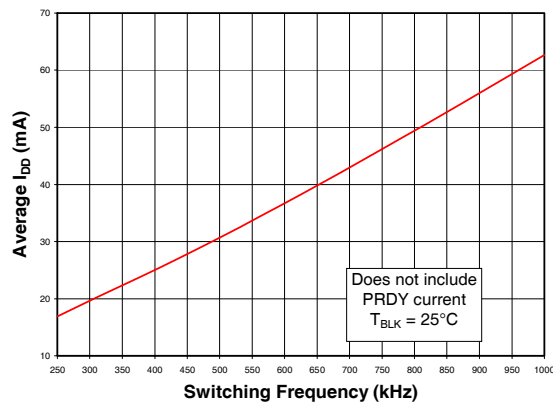


Fig. 7: I_{DD} vs. Frequency

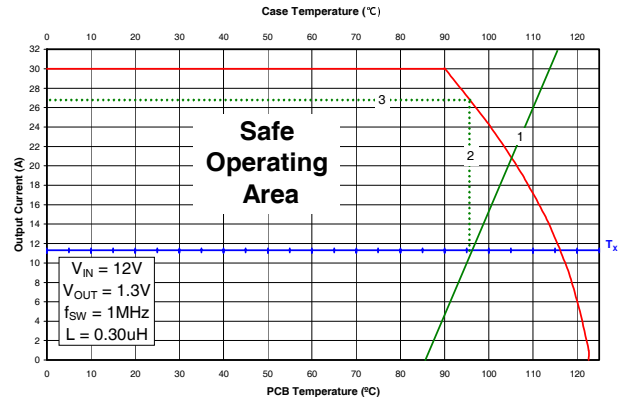
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Applying the Safe Operating Area (SOA) Curve

The SOA graph incorporates power loss and thermal resistance information in a way that allows one to solve for maximum current capability in a simplified graphical manner. It incorporates the ability to solve thermal problems where heat is drawn out through the printed circuit board and the top of the case.

Procedure

- 1) Draw a line from Case Temp axis at T_{CASE} to the PCB Temp axis at T_{PCB} .
- 2) Draw a vertical line from the T_x axis intercept to the SOA curve.
- 3) Draw a horizontal line from the intersection of the vertical line with the SOA curve to the Y axis. The point at which the horizontal line meets the y-axis is the SOA current.



Adjusting the Power Loss and SOA curves for different operating conditions

To make adjustments to the power loss curves in Fig. 1, multiply the normalized value obtained from the curves in Figs. 3, 4, 5 or 6 by the value indicated on the power loss curve in Fig. 1. If multiple adjustments are required, multiply all of the normalized values together, then multiply that product by the value indicated on the power loss curve in Fig. 1. The resulting product is the final power loss based on all factors. See example no. 1.

To make adjustments to the SOA curve in Fig. 2, determine your maximum PCB Temp & Case Temp at the maximum operating current of each iP2002PbF. Then, add the correction temperature from the normalized curves in Figs. 3, 4, 5 or 6 to the T_x axis intercept (see procedure no. 2 above) in Fig. 2. When multiple adjustments are required, add all of the temperatures together, then add the sum to the T_x axis intercept in Fig. 2. See example no. 2.

Operating Conditions for the following examples:

Output Current = 30A
Sw Freq= 900kHz

Input Voltage = 10V
Inductor = 0.2uH

Output Voltage = 3.3V

Example 1) Adjusting for Maximum Power Loss:

- (Fig. 1) Maximum power loss = 11W
- (Fig. 3) Normalized power loss for input voltage ≈ 0.98
- (Fig. 4) Normalized power loss for output voltage ≈ 1.28
- (Fig. 5) Normalized power loss for frequency ≈ 0.955
- (Fig. 6) Normalized power loss for inductor value ≈ 1.02

$$\text{Adjusted Power Loss} = 11W \times 0.98 \times 1.28 \times 0.955 \times 1.02 \approx \underline{13.44W}$$

Example 2) Adjusting for SOA Temperature:

- (Fig. 3) Normalized SOA Temperature for input voltage $\approx -0.8^{\circ}\text{C}$
- (Fig. 4) Normalized SOA Temperature for output voltage $\approx 8.4^{\circ}\text{C}$
- (Fig. 5) Normalized SOA Temperature for frequency $\approx -1.8^{\circ}\text{C}$
- (Fig. 6) Normalized SOA Temperature for inductor value $\approx 0.75^{\circ}\text{C}$

$$T_x \text{ axis intercept temp adjustment} = -0.8^{\circ}\text{C} + 8.4^{\circ}\text{C} - 1.8^{\circ}\text{C} + 0.75^{\circ}\text{C} \approx \underline{6.6^{\circ}\text{C}}$$

Assuming $T_{\text{CASE}} = 100^{\circ}\text{C}$ & $T_{\text{PCB}} = 90^{\circ}\text{C}$:

The following example shows how the SOA current is adjusted for a T_x increase of 6.6°C .

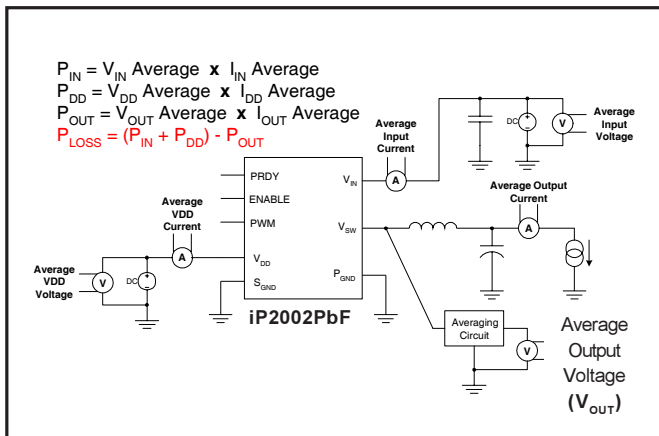
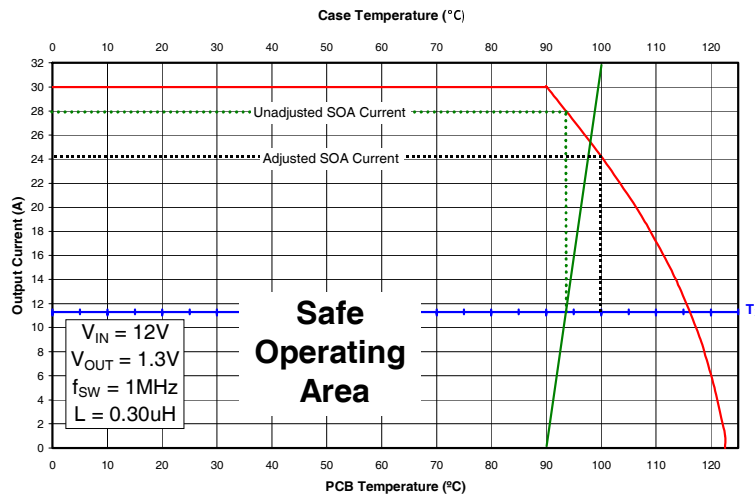


Fig. 8: Power Loss Test Circuit

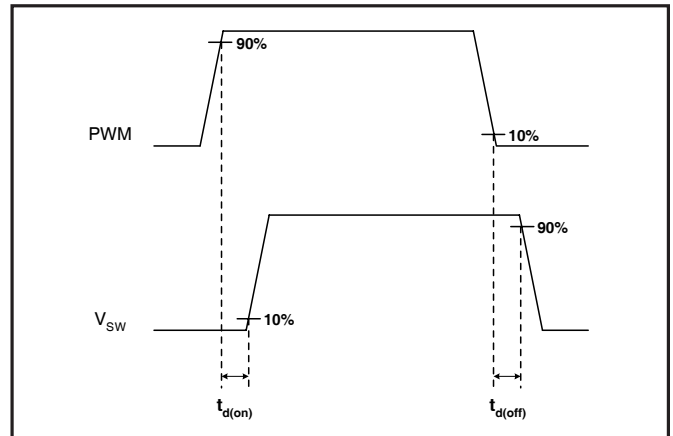


Fig. 9: Timing Diagram

| Quantity | Designator | Value 1 | Value 2 | Type 2 | Tolerance | Package | Mfr. | Mfr. Part No. |
|----------|--|------------|----------|----------------|--------------|-------------|--------------------|--------------------|
| 1 | C1 | 6800pF | 50V | X7R | 10% | 0805 | PHICOMP | 08052R682K9BB0 |
| 17 | C10 C11 C12 C13 C14 C3 C30 C31 C32 C33 C4 C46 C5 C6 C7 C8 C9 | 10.0uF | 16V | X5R | 10% | 1206 | Murata | GRM31CR61C106KC31B |
| 8 | C15 C16 C17 C18 C19 C20 C21 C22 | 100uF | 6.3V | X5R | 20% | 1210 | TDK | C3225X5R0J107M |
| 2 | C2 C29 | 10.0uF | 6.3V | X5R | 10% | 1206 | TDK | C3216X5R0J106K |
| 1 | C25 | 8.20pF | 50V | NPO | 3% | 0805 | PHICOMP | 0805CG829C9BB0 |
| 1 | C26 | 1800pF | 50V | X7R | 10% | 0805 | PHICOMP | 08052R182K9BB0 |
| 1 | C27 | 1.00uF | 16V | X7R | 10% | 0805 | MuRata | GRM40X7R105K016 |
| 1 | C28 | 0.010uF | 50V | X7R | 10% | 0805 | TDK | C2012X7R1H103KT |
| 1 | C34 | 0.100uF | 50V | X7R | 10% | 0805 | ROHM | MCH215C104KP |
| 4 | C35 C36 C37 C38 | 0.22uF | 6.3V | X5R | 10% | 0603 | TDK | C1608X5R0J224K |
| 3 | C39 C40 C41 | 330uF | 16V | WA series | 20% | SMD | Panasonic | EEF-WA1C331P |
| 5 | C42 C43 C44 C45 C47 | Open | - | - | - | - | - | - |
| 3 | R1 R2 R31 | 3.92K | 1/8W | thin film | 0.10% | 0805 | BC Component | 2312-241-73922 |
| 5 | R10 R11 R12 R13 R35 | 0 | 1/8W | thick film | <50m | 0805 | ROHM | MCR10EZJH000 |
| 9 | R16 R17 R18 R19 R21 R23 R25 R27 R34 | 10.0K | 1/8W | thick film | 1% | 0805 | KOA | RK73H2A1002F |
| 2 | R3 R32 | 4.42K | 1/8W | thin film | 0.10% | 0805 | BC Component | 2312-241-74422 |
| 1 | R33 | 30.1K | 1/8W | thick film | 1% | 0805 | KOA | RK73H2A3012F |
| 1 | R4 | 20.0K | 1/8W | thick film | 1% | 0805 | KOA | RK73H2A2002F |
| 4 | R5 R7 R8 R9 | 2.49K | 1/8W | thick film | 1% | 0805 | KOA | RK73H2A2491F |
| 1 | R6 | 200 | 1/8W | thick film | 1% | 0805 | KOA | RK73H2A2000F |
| 7 | R22 R24 R26 R28 R29 R30 R36 | Open | - | - | - | - | - | - |
| 2 | D1 D2 | 30V | 200mA | schottky | - | sot23 | Central | CMPD3003A |
| 1 | D5 | 40V | 2.1A | schottky | - | D-64 | IRF | 10MQ040N |
| 1 | D6 | 30V | 100mA | schottky | - | sot23 | Central | CMPSH-3 |
| 4 | L1 L2 L3 L4 | 0.3uH | 36A | ferrite | 20% | SMT | Panasonic | ETQP2H0R3BFA |
| 1 | L5 | 15uH | 0.70A | ferrite | 20% | SMT | Coilcraft | 1008PS-153M |
| 1 | U1 | 4.5 - 5.5V | 0.8 - 5V | PWM controller | 0 - 70°C | 16 Ld SOIC | Intersil | ISL6558CB |
| 4 | U2 U3 U4 U5 | 30A | - | Power Block | - | 11mm x 11mm | International Rect | iP2002PbF |
| 1 | U6 | 4.7 - 25V | 1.8 - 5V | PWM controller | -40 to +85°C | S6 | Linear Technology | LT1616 |

4-Phase Reference Design Bill of Materials

Refer to the following application notes for detailed guidelines and suggestions when implementing iPOWIR Technology products:

AN-1028: Recommended Design, Integration and Rework Guidelines for International Rectifier's iPOWIR Technology BGA Packages

This paper discusses the assembly considerations that need to be taken when mounting iPOWIR BGA's on printed circuit boards. This includes soldering, pick and place, reflow, inspection, cleaning and reworking recommendations.

AN-1029: Optimizing a PCB Layout for an iPOWIR Technology Design

This paper describes how to optimize the PCB layout design for both thermal and electrical performance. This includes placement, routing, and via interconnect suggestions.

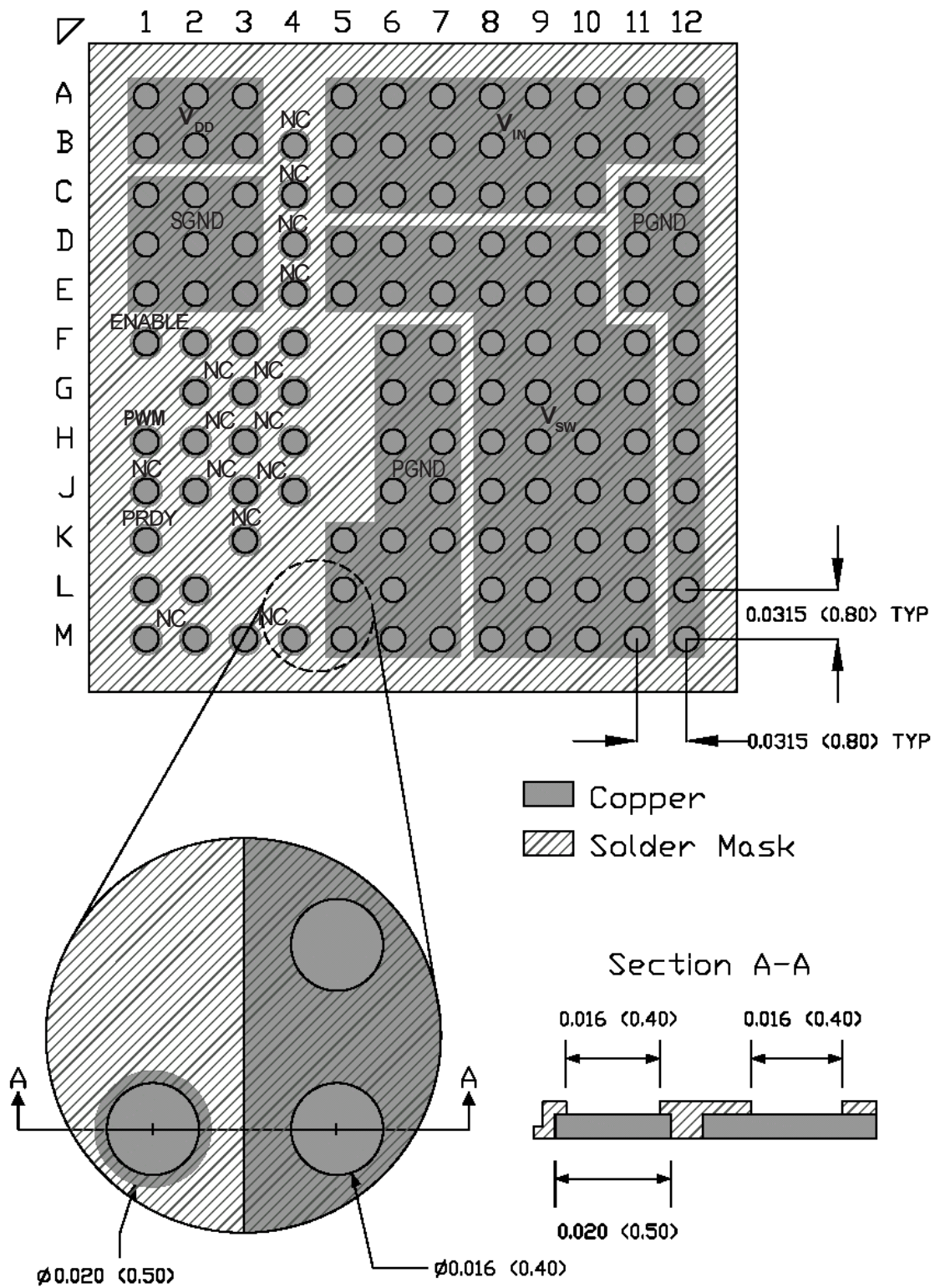
AN-1030: Applying iPOWIR Products in Your Thermal Environment

This paper explains how to use the Power Loss and SOA curves in the data sheet to validate if the operating conditions and thermal environment are within the Safe Operating Area of the iPOWIR product.

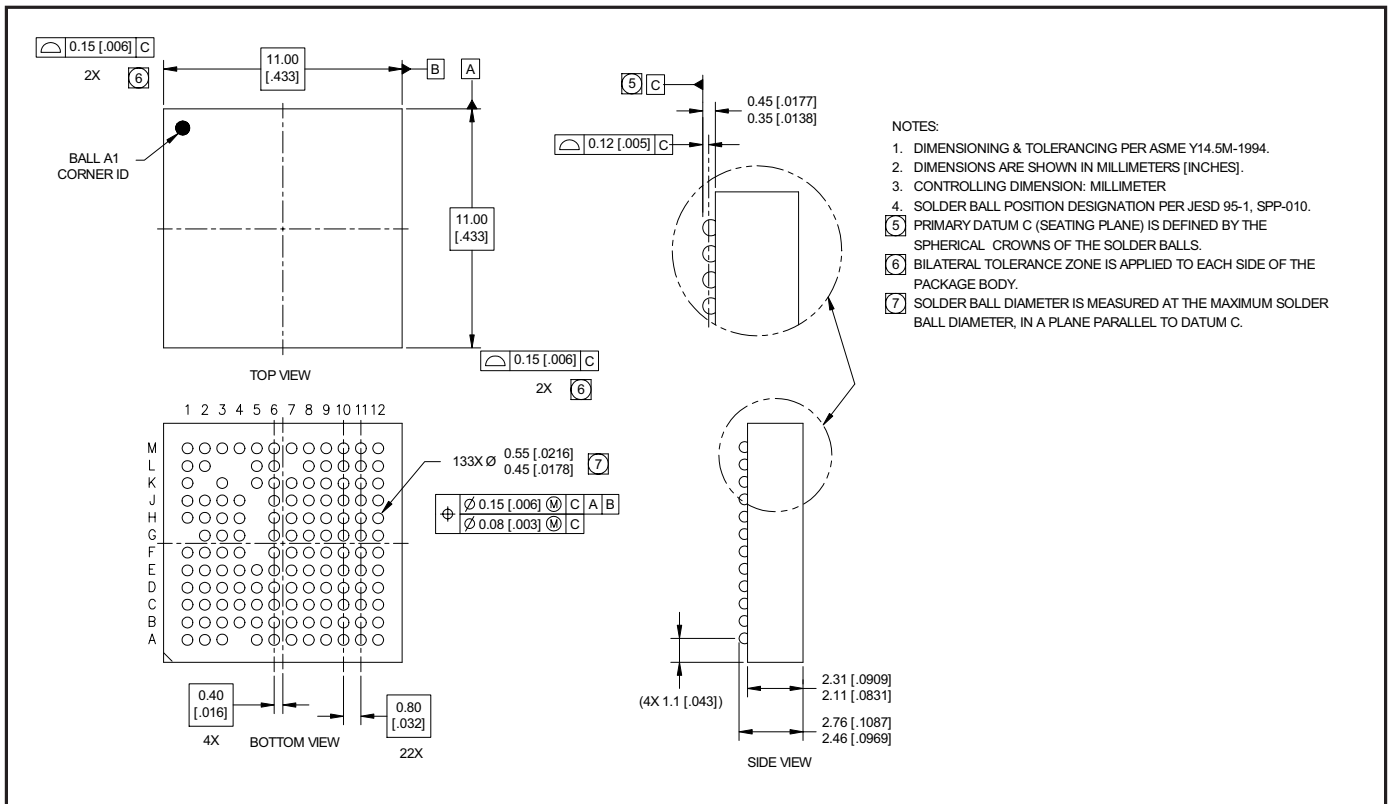
AN-1047: Graphical solution for two branch heatsinking Safe Operating Area

Detailed explanation of the dual axis SOA graph and how it is derived.

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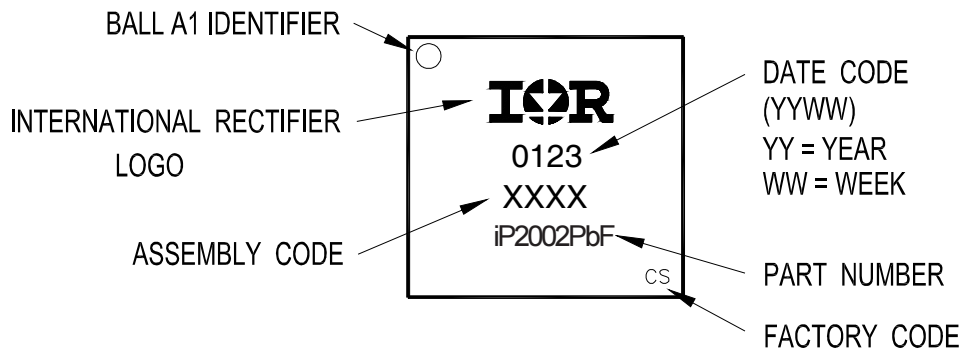


Dimensions shown in inches (millimeters)
Recommended PCB Footprint (Top View)

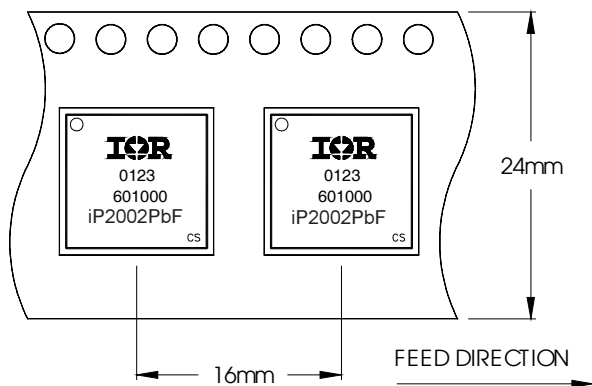


Mechanical Drawing

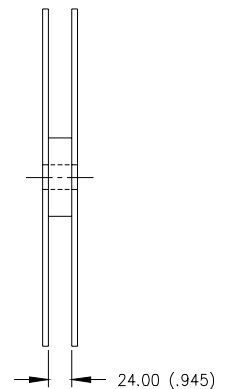
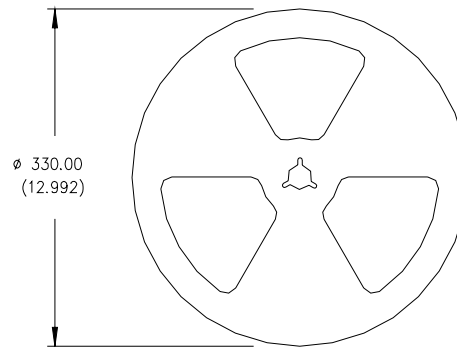
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Part Marking



- NOTES:
 1. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES:
 1. CONTROLLING DIMENSION: MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Tape & Reel Information

*Data and specifications subject to change without notice.
 This product has been designed and qualified for the industrial market.
 Qualification Standards can be found on IR's Web site.*

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